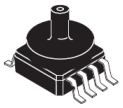
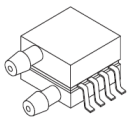
MPXV7025DP, MPXV7025GC6

Datasheet

Integrated silicon pressure sensor on-chip signal conditioned, temperature compensated and calibrated



CASE 482A-01



CASE 1351-01

Features

- 5.0% Maximum Error Over 0°C to 85°C
- Ideally Suited for Microprocessor or Microcontroller-Based Systems
- Temperature Compensated Over –40°C to +125°C
- Thermoplastic (PPS) Surface Mount Package
- Patented Silicon Shear Stress Strain Gauge
- Available in Differential and Gauge Configurations

Applications

- Respiratory Systems
- Process Control
- Patient Monitoring
- Remote Monitoring Devices

Description

The MPXV7025 series piezoresistive transducer is a state-of-the-art monolithic silicon pressure sensor designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This patented, single element transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

1 Ordering information

Table 1. **Ordering information**

Device Name	Package Options	Case No.	# of Ports				Pressure Type		Device Marking
			None	Single	Dual	Gauge	Differential	Absolute	
Small Outline Package (MPXV7025 Series)									
MPXV7025GC6U	Tape & Reel	482A		•		•			MPXV7025G
MPXV7025DP	Trays	1351			•		•		MPXV7025DP

2 Operating Characteristics

Table 2. Operating Characteristics (V_S = 5.0 Vdc, T_A = 25°C unless otherwise noted, P1 > P2. Decoupling circuit shown in Figure 3 required to meet electrical specifications.)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range(1)		P_{OP}	-25	—	25	kPa
Supply Voltage(2)		V_S	4.75	5.0	5.25	Vdc
Supply Current		I_o	—	7.0	10	mAdc
Minimum Pressure Offset(3) @ V_S = 5.0 Volts	(0 to 85°C)	V_{off}	0.116	0.25	0.384	Vdc
Full Scale Output(4) @ V_S = 5.0 Volts	(0 to 85°C)	V_{FSO}	4.610	4.75	4.890	Vdc
Full Scale Span(5) @ V_S = 5.0 Volts	(0 to 85°C)	V_{FSS}	—	4.5	—	Vdc
Accuracy	(0 to 85°C)	—	—	—	±5.0	$\%V_{FSS}$
Sensitivity		V/P	—	90	—-	mV/kPa
Response Time(6)		t_R	—	1.0	—-	ms
Output Source Current at Full Scale Output		I_{o+}	—	0.1	—-	mAdc
Warm-Up Time(7)		—	—	20	—-	ms
Offset Stability(8)		—	—	±0.5	—-	$\%V_{FSS}$

1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range.
3. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
4. Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
5. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
8. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

3 Maximum Ratings

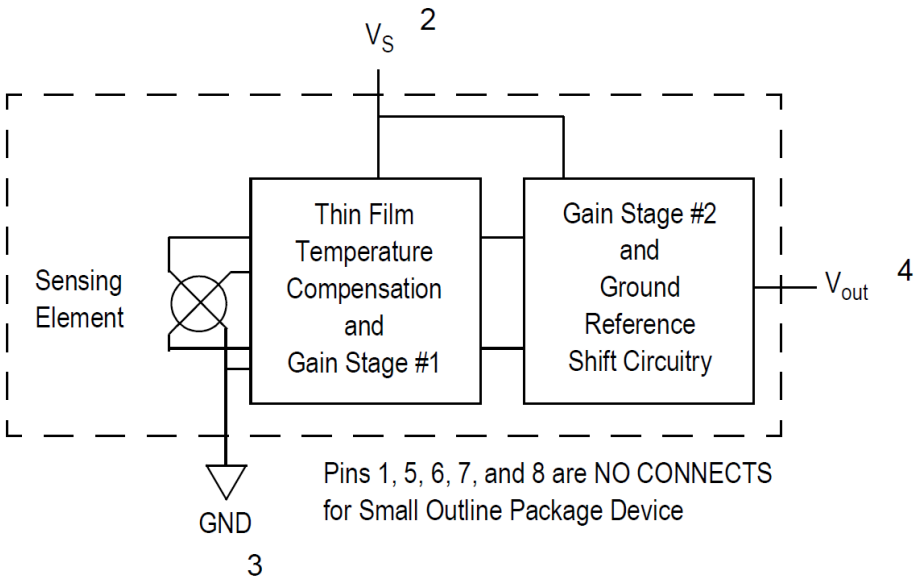
Table 3. Table 2. Maximum Ratings(1)

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	Pmax	200	kPa
Storage Temperature	Tstg	–40 to +125	°C
Operating Temperature	TA	–40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

Figure 1. Integrated Pressure Sensor Schematic



4 On-chip Temperature Compensation and Calibration

The MPXV7025 series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 2 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0°C to 85°C using the decoupling circuit shown in Figure 3. The output will saturate outside of the specified pressure range.

Figure 3 shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended

Figure 2. Output versus Pressure Differential

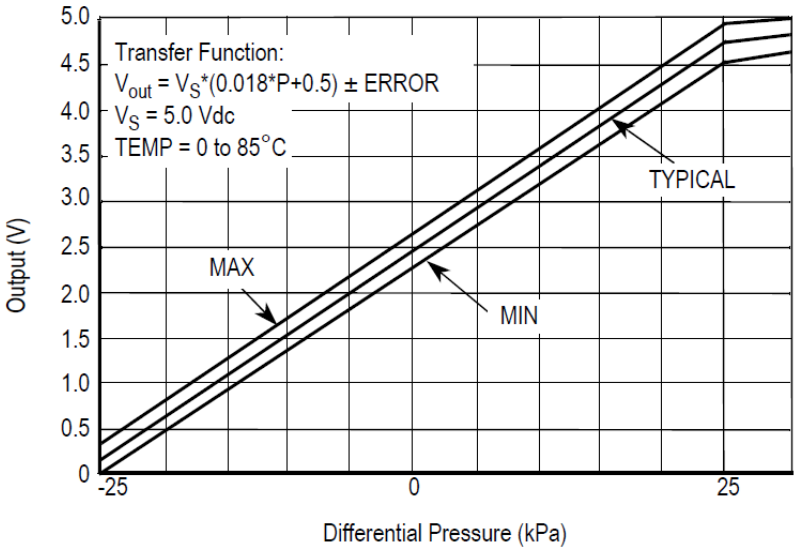


Figure 3. Recommended Power Supply Decoupling and Output Filtering (For additional output filtering, please refer to Application Note AN1646.)

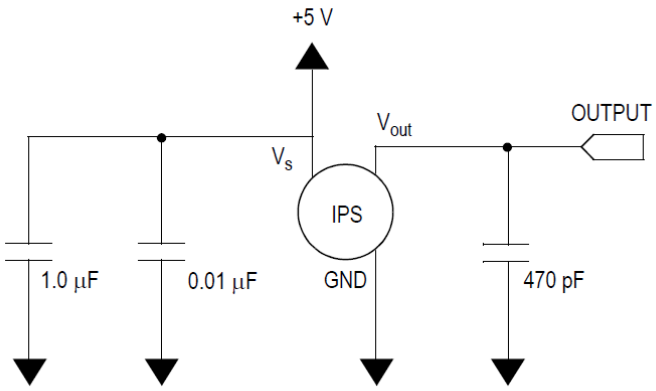
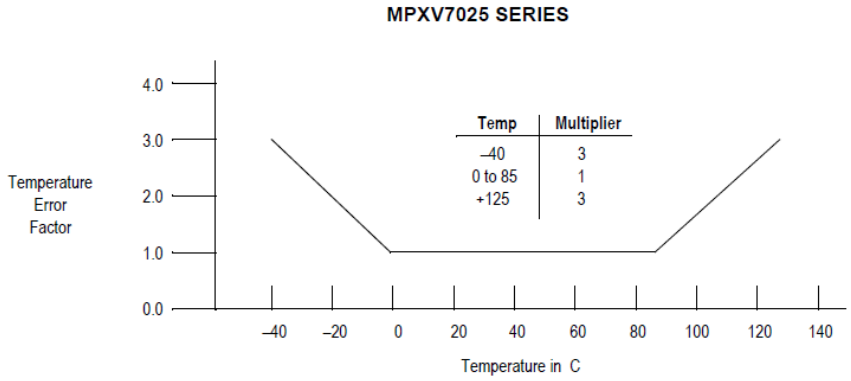


Figure 4. Transfer Function

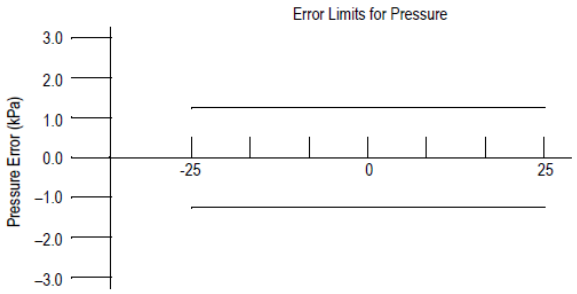
Nominal Transfer Value: $V_{out} = V_S (P \times 0.018 + 0.5)$
$\pm$ (Pressure Error x Temp. Factor x 0.018 x V_S)
$V_S = 5.0\ V \pm 0.25\ Vdc$

Figure 5. Temperature Error Band



NOTE: The Temperature Multiplier is a linear response from 0° to –40°C and from 85° to 125°C.

Figure 6. Pressure Error Band



Pressure	Error (Max)
-25 to 25 (kPa)	±1.25 (kPa)

5 PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

ST designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluorosilicone gel which protects the die from harsh media. The pressure sensor is designed to operate with positive differential pressure applied, P1 > P2.

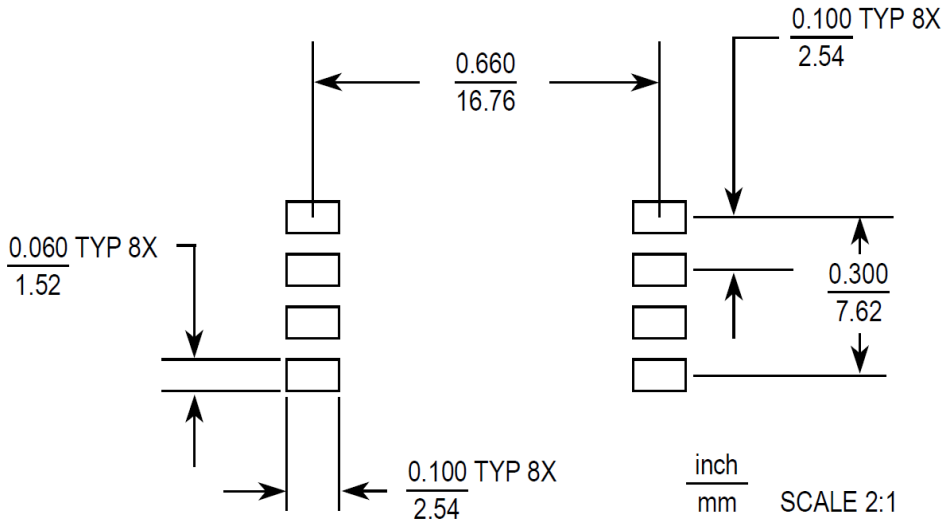
The Pressure (P1) side may be identified by using the following table:

Part Number	Case Type	Pressure (P1) Side Identifier
MPXV7025GC6U	482A	Side with Port Attached
MPXV7025DP	1351	Side with Part Marking

6 MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

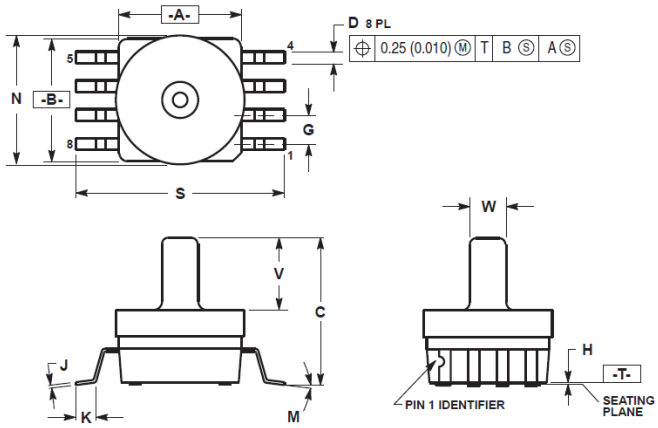
Surface mount board layout is a critical portion of the total design. The footprint for the surface mount packages must be the correct size to ensure proper solder connection interface between the board and the package. With the correct footprint, the packages will self align when subjected to a solder reflow process. It is always recommended to design boards with a solder mask layer to avoid bridging and shorting between solder pads.

Figure 7. Small Outline Package Footprint



7 PACKAGE DIMENSIONS

Figure 8. CASE 482A-01 ISSUE A SMALL OUTLINE PACKAGE



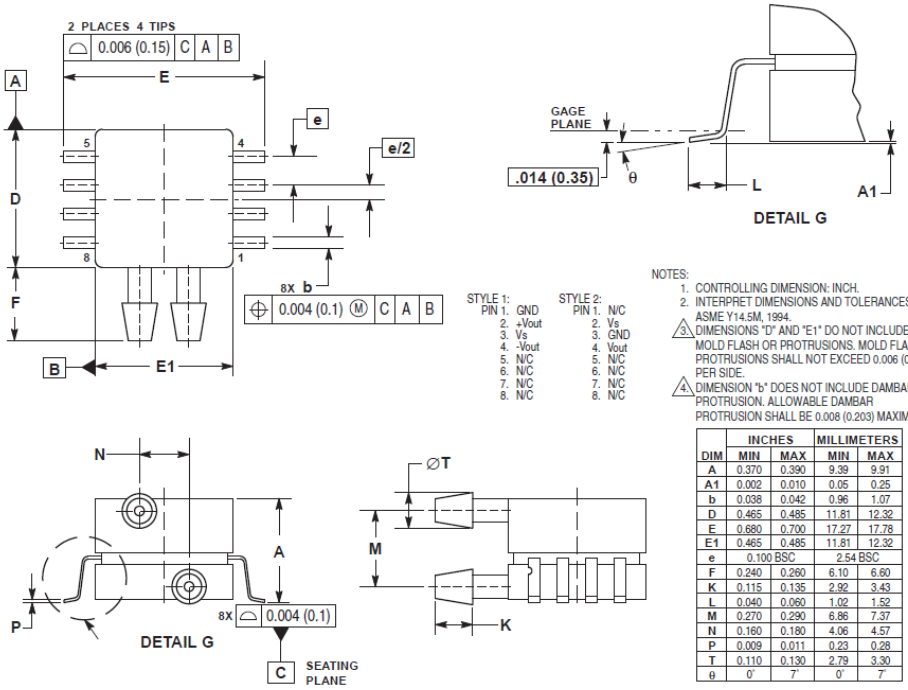
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.500	0.520	12.70	13.21
D	0.038	0.042	0.96	1.07
G	0.100 BSC		2.54 BSC	
H	0.002	0.010	0.05	0.25
J	0.009	0.011	0.23	0.28
K	0.061	0.071	1.55	1.80
M	0°	7°	0°	7°
N	0.444	0.448	11.28	11.38
S	0.709	0.725	18.01	18.41
V	0.245	0.255	6.22	6.48
W	0.115	0.125	2.92	3.17

CASE 482A-01
ISSUE A
SMALL OUTLINE PACKAGE

Figure 9. CASE 1351-01 ISSUE O SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS



NOTES:
1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 (0.152) PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.008 (0.203) MAXIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.370	0.390	9.39	9.91
A1	0.002	0.010	0.05	0.25
b	0.038	0.042	0.96	1.07
D	0.465	0.485	11.81	12.32
E	0.680	0.700	17.27	17.78
E1	0.465	0.485	11.81	12.32
e	0.100 BSC		2.54 BSC	
F	0.240	0.260	6.10	6.60
K	0.115	0.135	2.92	3.43
L	0.040	0.060	1.02	1.52
M	0.270	0.290	6.86	7.37
N	0.160	0.180	4.06	4.57
P	0.009	0.011	0.23	0.28
T	0.110	0.130	2.79	3.30
θ	0°	7°	0°	7°

CASE 1351-01
ISSUE O
SMALL OUTLINE PACKAGE

Revision history

Table 4. **Document revision history**

Date	Revision	Changes
19-May-2026	1	Initial release from ST, rebranded NXP document

Contents

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